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Abstract

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Removal of Masking Tape from Lead Frames



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A resin body is moulded around a die located on the front surface of a lead
5 frame, and subsequently masking tape adhered to the rear surface of the lead
frame is peeled away. While the tape is peeled away, the front surface of the
lead frame is clamped by a surface which contains, or which can be deformed
to contain, a recess for receiving the resin body. The peeling is performed by
10 firstly separating an edge portion of the tape from the lead frame by a
diagonal motion, and subsequently moving the edge portion across the lead
frame so as to peel back the tape until its adhered surface faces away from
the lead frame. A retrieval plate is urged against the adhered surface, so that
the adhered surface becomes adhered to the retrieval plate. This process is
repeated for successive lead frames, so that a stack of masking tape sections
15 is formed on the retrieval plate.

Fig. 4